Hirata

Security code : 6258 February 2025

Financial Results Explanatory Materials

FY2024 (March 2025)

Note : This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail.

Hirata

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Hirata

Company Profile

Company Name	HIRATA Corporation
Address	111 Hitotsugi, Ueki, Kita, Kumamoto, 861-0198 Japan
Representatives	Yuichiro Hirata, President
Date Established	December 29, 1951
Capital	2,633 million yen
Our business	Manufacture and sales of various manufacturing systems, industrial robots and logistic equipment
Stock Exchange Listings	Tokyo Stock Exchange, Prime Market (Symbol:6258)
Employees	Consolidated 2,347 Non-Consolidated 1,502 ** As of March 31, 2025
Plants and office	7 bases in Japan(4 bases in Kumamoto 1 each in Tochigi, Shiga, Tokyo)
Subsidiaries	3 subsidiaries in Japan(2 in Kumamoto, 1 in Tokyo) 9 overseas subsidiaries(America、Mexico、Singapore、Thailand、Malaysia、2 in China、Taiwan、Germany)

% We start liquidation procedures of a subsidiary in Germany on May 1, 2025.



I. FY2024 Full Year Results (Consolidated)

I. FY2024 Full Year Results (Consolidated) Financial Summary

(Units in millions of Yen)

• Order received for semiconductor-related products has remained strong since the second quarter, but the orders for automobile-related products have decreased due to customer development delays, leading to an overall decline compared to the previous period.

- Sales Sales increased overall compared to the previous period, driven by the progress in production of orders received, particularly in the automotive sector.
- Operating profit increased compared to the previous period. The reasons for this include increased profits due to higher sales, and although the operating profit margin for semiconductor-related activities decreased, it improved for automobile-related activities.

FY2023 FY2024 YoY Change Actual results Actual results Amount of +/-Percentage of +/-**Orders Received** 86.239 79,512 ▲6,726 ▲7.8% Net Sales 82,839 88,483 5,644 6.8% 6.898 6.047 **Operating Profit** 850 14.1% (Profit ratio) (7.3%)(7.8%)**Ordinary Profit** 6.259 6.889 10.1% 629 Profit attributable 4,344 4,778 433 10.0% to owners of parent Backlog of Orders 65,404 56,433 ▲8,971 ▲13.7%

I. FY2024 Full Year Results (Consolidated) Factor Analysis on Changing Operating Profit

- Operating profit increased approximately 850 million yen from the same period of the previous year.
 - Main factors for increase : Increase in sales
 - Main factors for decrease : Increase in the selling, general and administrative expenses



Impact of increase in cost ratio

Cost ratio 78.5% ⇒ 78.6%

Main factors for the deterioration of the cost ratio

Hirata

- Increase in labor costs due to wage hikes and staff increases
- Increase in depreciation expenses
- The impact of rising prices

Main factors for the improvement of the cost ratio

- Price transfer promotion
- Improvement of productivity through skill enhancement

2 Impact of increase in SG&A expenses

Main factors for the increase in SG&A expenses

• Increase in labor costs due to wage hikes and staff increases

Results by Segment

(Units in millions of Yen)		FY2023	FY2024	Amount of +/-	Percentage of +/-
	Total	86,239	79,512	▲6,726	▲ 7.8%
Deside	Automobile	44,492	34,111	▲10,381	▲23.3%
Received	Semiconductor	25,107	29,730	4,622	18.4%
orders	Other Automatic Labor- saving equipment	14,357	13,351	▲1,006	▲7.0%
	Others	2,281	2,319	37	1.7%
	Total	82,839	88,483	5,644	6.8%
	Automobile	36,984	43,059	6,074	16.4%
Net Sales	Semiconductor	27,390	30,186	2,796	10.2%
Net Sales	Other Automatic Labor- saving equipment	16,083	13,096	▲2,986	▲18.6%
	Others(including elimination)	2,381	2,141	▲239	▲10.1%
	Total	6,047	6,898	850	14.1%
	Automobile	1,651	4,194	2,543	154.0%
Operating	Semiconductor	4,450	2,857	▲1,592	▲35.8%
profit	Other Automatic Labor- saving equipment	119	▲101	▲221	-
	Others	▲173	▲52	120	-
	Total	65,404	56,433	▲8,971	▲ 13.7%
	Automobile	39,150	30,202	▲8,947	▲22.9%
Backlog	Semiconductor	19,470	19,013	▲456	▲2.3%
or orders	Other Automatic Labor- saving equipment	6,295	6,549	254	4.0%
	Others	488	667	178	36.5%

Results by Segment : Automobile-related

- Order received
 Several large projects (EV and internal combustion engines) were postponed to the next period due to customer development delays, resulting in a decrease in received orders compared to the previous period.
 Sales
 Production of EV-related projects (mainly related to EDU and batteries) and internal combustion engine projects have progressed. Additionally, the expanded production space has also contributed to the increase in production. As a result, sales have increased.
 Operating projects and improvements in revenue, the promotion of price transfer in individual projects and improvements in
 - profit skill levels have led to enhanced profitability, resulting in an increase in operating profit compared to the previous period.

FY2023		FY20)24	YoY Change			
		Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Receive	d Orders	44,492	-	34,111	-	▲10,381	▲23.3%
	EV	25,112	56.4%	24,336	71.3%	▲775	▲3.1%
	Others	19,380	43.6%	9,774	28.7%	▲9,605	▲49.6%
Net Sal	es	36,984	-	43,059	-	6,074	16.4%
	EV	27,627	74.7%	28,220	65.5%	593	2.1%
	Others	9,357	25.3%	14,838	34.5%	5,481	58.6%
Backlog	of orders	39,150	-	30,202	_	▲8,947	▲22.9%
Operatin	g profit	1,651	-	4,194	-	2,543	154.0%
Operating p	profit ratio	4.5%	-	9.7%	_	-	-

Results by Segment : Semiconductor-related

- Order received Due to the expanding demand for generative AI, the order received increased compared to the previous period, maintaining strong performance since the second quarter.
- Sales In response to the increase in orders, production, particularly in wafer handling related business, progressed, resulting in a rise in sales compared to the previous period.
- Operating profit In addition to the decrease in high-profit margin projects, the rise in material prices and the delay in passing on costs have worsened the cost ratio. Furthermore, the allocation of warranty costs for certain products has also had an impact, resulting in a decrease in operating profit compared to the previous period.

(Units in millions of Yen)

	FY2023		FY20	24	YoY Change	
	Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Received Orders	25,107	-	29,730	-	4,622	18.4%
Wafer transfer	16,646	66.3%	21,178	71.2%	4,532	27.2%
Others	8,460	33.7%	8,551	28.8%	90	1.1%
Net Sales	27,390	-	30,186	-	2,796	10.2%
Wafer transfer	18,836	68.8%	21,258	70.4%	2,422	12.9%
Others	8,553	31.2%	8,927	29.6%	374	4.4%
Backlog of orders	19,470	-	19,013	-	▲456	▲2.3%
Operating profit	4,450	-	2,857	-	▲1,592	▲35.8%
Operating profit ratio	16.2%	-	9.5%	-	-	

I. FY2024 Full Year Results (Consolidated) Results by Segment : Other Automatic Labor-saving Equipment

- Order received The order received decreased compared to the previous period due to a decline in capital investment related to home appliances and logistics equipment such as tires.
 - Sales decreased compared to the previous period as a result of declines in FPD-related and logistics-related segments.
- Sales
 Operating profit
 - Operating profit decreased compared to the previous period as a result of the decline in orders and sales, despite efforts to control costs and selling, general, and administrative expenses; this was due to a deterioration in the cost ratio for some projects.

		(Units	in millions of Yen)				
	FY20)23	FY20	FY2024		YoY Change	
	Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-	
Received Orders	14,357	-	13,351	-	▲1,006	▲7.0%	
Net Sales	16,083	-	13,096	-	▲2,986	▲18.6%	
Backlog of orders	6,295	-	6,549	-	254	4.0%	
Operating profit	119	-	▲101	-	▲221	-	
Operating profit ratio	0.7%	-	▲0.8%	-	-	-	

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Balance Sheet

(Units in millions of Yen)

Assets	FY2023	FY2024	YoY change	Liabi
Current Assets	88,554	88,035	▲518	Current
Cash & deposits	10,652	12,882	2,229	Fixed lia
Trade receivables, etc.	59,504	56,561	▲2,942	Total Liabilit
Inventories	14,264	15,510	1,245	Net A
Others	4.131	3.080	▲1.050	
	.,			Total I Assets
Assets	42,233	42,243	9	Main fa
Tangible fixed assets	27,437	26,592	▲844	• Current
Intangible fixed assets	904	1,160	255	Current
Investment & other assets	13,891	14,489	598	labilities
Total Assets	130,787	130,278	▲509	 Fixed liabilities

Liabilities	FY2023	FY2024	YoY change
Current liabilities	49,864	43,295	▲6,569
Fixed liabilities	15,621	18,143	2,522
Total Liabilities	65,485	61,439	▲4,046
Net Assets			
Total Net Assets	65,302	68,839	3,536
Main factors for increase/decrease			

- Current The collection of accounts receivable has progressed, assets leading to an increase in cash and deposits.
- Current The repayment of short-term borrowings and the liabilities progress in production have resulted in a decrease in contract liabilities, leading to a reduction in current liabilities.
 - the increase in large projects and long-term projects bilities has led to an increase in long-term borrowings, which has also resulted in an increase in fixed liabilities.



II. FY2025 Full Year Forecasts (Consolidated)

Full Year Forecast

• We anticipate an increase in revenue to 96 billion yen and an increase in operating profit to 8.4 billion yen for the fiscal year 2025 (ending March 2026).

(Units in millions of Yen)

	FY2024	FY2025	YoY C	hange
	Results	Full year forecast	Amount of +/-	Percentage of +/-
Net Sales	88,483	96,000	7,516	8.5%
Automobile-related	43,059	43,000	▲59	▲0.1%
Semiconductor-related	30,186	36,000	5,813	19.3%
Other Automatic Labor- saving Equipment	13,096	15,000	1,903	14.5%
Others	2,141	2,000	▲141	▲6.6%
Operating Profit (x)	6,898 (7.8%)	8,400 (8.8%)	1,501	21.8%
Ordinary Profit (x)	6,889 (7.8%)	8,200 (8.5%)	1,310	19.0%
Profit attributable to owners of parent (x)	4,778 (5.4%)	5,700 (5.9%)	921	19.3%

<u> Highlights of Full Year Forecast – Net Sales</u>

- For the fiscal year 2025, we forecast sales revenue to be 96 billion yen, an increase of 8.5% compared to the previous period (the highest ever).
- We expect increased sales primarily in the semiconductor-related sector.

1 Automobile-related sector 43 billion yen (almost the same compared to the previous year)

•We anticipate continued solid demand, primarily for ICE and EV batteries.

•As a core business for Hirata, we aim to improve productivity and ensure appropriate price transfer.

2 Semiconductor-related sector 36 billion yen (+5.8 billion yen compared to the previous year)

We expect semiconductor demand related to generative AI to remain strong in fiscal year 2025.
By developing new products and enhancing supply capacity, we will respond to market needs and aim to increase our market share.

3 Other Automatic Labor-saving Equipment 15 billion yen (+1.9 billion yen compared to the previous year)

• Leveraging our past experiences, we will focus on responding to high-profit inquiries and opportunities.

II. FY2025 Full Year Results (Consolidated) Highlights of Full Year Forecast - Analysis of factors influencing the increase or decrease in operating profit

- Operating profit increased approximately 1.5 billion yen from the same period of the previous year.
 - Main factors for increase : Increase in sales, improvements in cost ratio
 - Main factors for decrease : Increase in the selling, general and administrative expenses



Cost ratio 78.6% ⇒ 77.2%

Main factors for improvements of cost ratio

- Price transfer promotion
- Improvement of productivity through skill

2 Impact of increase in SG&A expenses

Main factors for increase in SG&A expenses

- Increase of R&D expenses
- Increase in labor costs due to wage hikes and
- Increase of system-related expenses, etc.



II. Capital Policy, etc.

Hirata Transition and Forecast of Dividends and Dividend Ratio per Share

						(Units in Yen)
	FY2020	FY2021	FY2022	FY2023	FY 2024	FY 2025 forecast
Dividends per Share	65.00	65.00	90.00	100.00	120.00	65.00
Dividend Ratio (%)	16.6	25.2	21.9	23.9	25.9	35.3
Our approach to dividends>				split ares for share)		

Regarding the dividend for the fiscal year 2024, it has been resolved at the board meeting held on May 9, 2025, to set the dividend at 120 ven per share.

For dividends from the fiscal year 2025 onwards, based on the growth strategy aimed at enhancing corporate value as outlined in the medium-term management plan (FY2025-2027), we have established the allocation of growth investments and shareholder returns within our cash allocation policy, and decided to raise the target consolidated dividend payout ratio to a level from 20% to 35%.

For the fiscal year 2025's dividend, we anticipate a year-end dividend of 65 year.

*As of the reference date of March 31, 2025, and with an effective date of April 1, 2025, a share split is being conducted at a ratio of 3 shares for each common stock share



IV. Reference Data 1 Net Sales Composition Ratio by Business Segment



^{*}We changed our business classifications effective from FY2022.

IV. Reference Data 2 Quarterly Trends by Business Segment [Received Orders]



IV. Reference Data 3 Quarterly Trends by Business Segment [Net Sales]



Hirata Quarterly Trends by Business Segment [Operating Profit]

*Others includes elimination



IV. Reference Data 5 R&D, CAPEX, Depreciation and Amortization



IV. Reference Data 6 **Production space (Non-consolidated ·End of period)**

- We are actively working on the continuous expansion of production space to increase our production capacity.
- We secure production space in Yamaga City, which is adjacent to Kumamoto City, for the fiscal year 2024 as well.



Hirata Number of recruits • employees (Non-consolidated • End of period)

- In anticipation of business expansion, we are committed to ensuring a continuous supply of talented professionals.
- We are working on talent retention through various measures such as wage improvements, workstyle reforms, enhancing employee benefits, and providing quality education and training opportunities.



External Environment and growth opportunities

Changes in the environment surrounding Hirata	Implications for our business		Hirata's strengths	
Serious deepening of labor shortages Surge in labor costs	Expansion of automation and labor-saving needs		Long-term	Pole
Innovations in digital technologies centered around AI	Shift towards building equipment based on digitalization in production sites		relationships with global top companies Expertise, technologies,	We recognize
Partial slowdown in the growth of the EV market Automakers' all-around strategies	Response to advanced automation needs across a wide range of automobile-related equipment	×	and resources developed as a manufacturer of production equipment	that expectations for our automation and labor-saving
Expansion of the semiconductor market and rapid technological evolution	 Development of high value- added products in response to changing customer needs 		Ability to continuously meet customer needs for	solutions from customers will continue to grow.
Growing importance of	Product development and business cultivation that meet needs such as reducing environmental impact		A trusted position in an industry with high	
Demands for enhancing corporate value from the — market	 Early realization of a high- profit structure through the pursuit of earning power 		barriers to entry	

The list of large-scale purchase order projects we disclosed started from FY2023 and onwards

Business segment	Disclosure date		Outline of the equipment	Amount
	2023	June	EDU assembly equipment for EVs	More than 8 billion yen
Automobile -related	2024	January	Battery charging and discharging related equipment for EVs	More than 4 billion yen
		February	Engine assembly equipment for internal combustion engines	Approximately 13 billion yen
		May	Battery charging and discharging related equipment for EVs	Approximately 2.5 billion yen
		August	Battery charging and discharging related equipment for EVs	Approximately 5.6 billion yen
		August	EDU assembly equipment for EVs	Approximately 8.7 billion yen

- The cumulative order amount of battery charging and discharging related equipment since the fiscal year 2022 has exceeded 15 billion yen.
- Our ability to handle large-scale projects and the track record of delivering battery charging and discharging related equipment for EVs have been highly evaluated, leading to continuous order acquisition.

IV. Reference Data 10 Strengthening our efforts in ESG management

2023	Apr.	The Sustainability Promotion Committee is established.
		Sustainability page is established in our web page and the dissemination of ESG information is been strengthened.
	Sep.	We sign the UN Global Compact.
	Oct.	Human rights due diligence is implemented.
	Nov.	We express our support for the Keidanren's "Charter of Corporate Behavior."
2024	Jan.	Code of Conduct of the Hirata Group is established.
		Human Rights Respect Working Group within the Sustainability Promotion Committee is established.
	Jun.	Selected as a constituent stock for: 「FTSE Blossom Japan Index」 「FTSE Blossom Japan Sector Relative Index」
	Nov.	We have endorsed the Keidanren Declaration for Biodiversity and Guideline.
2025	Mar.	We have obtained the "Silver" rating in the EcoVadis sustainability assessment.

Hirata Business Overview : Main products of automobile-related business

• We continue to receive orders from North American automakers (Big three), North American emerging EV manufacturers, domestic electronic components manufacturers, focusing on EV related.

Main/Expansion Fields of EV-related business

Production equipment handled by Hirata



*Completed product image



EDU assembly equipment Main field

We manufacture EV-drive parts assembly equipment called EDU (Electric Drive Unit) combined with in-vehicle motors and gearboxes.

2 IGBT·Inverter assembly equipment

We manufacture in-vehicle electronic components mounted on EVs and transmissions such as IGBT and inverters.

Battery-related assembly equipment Expansion field

Main field



(Cell charging / discharge process)

We manufacture conveying equipment for charging and discharging processes that are part of the battery cell progress.

Main customers, competitors, superiority

EDU	assembly
equ	ipment

North America

Customers North American automakers (Big three)

 North American emerging EV manufacturers

IGBT·Inverter assembly equipment	B a
Japan	_
Customers	(
Domestic electronic	[
components manufacturers	l r

3

Battery-related assembly equipment (cell charging/discharging process
Japan
Customers
Domestic battery
manufacturers

Hirata's superiority

- Technical capabilities to handle large facilities, some of which exceed 1 km in total length, solely in-house
- A vast factory that allows us to build the customer's production line in our factory and install it on site after verifying the production capacity and quality
- Integrated system from development to production and maintenance
- Engineering ability to respond to customer requests

IV. Reference Data 12 Business Overview : Charging and discharging related equipment

- We have charge and discharge equipment that handles the final process of cell manufacturing, which is the "charging and discharging" process.
- We have a competitive advantage in systematization utilizing conveyance and stocking technologies.

Battery manufacturing process



Hirata Business Overview : Main products of semiconductor-related business

• We continue to receive orders mainly for wafer transport devices for domestic device manufacturers and handling devices between inspection devices

Main/Expansion Fields of Semiconductor-related business



Main customers, competitors, superiority

Customers Customers Domestic manufacturing equipment manufacturers • North American device makers • Domestic inspection equipment manufacturers	Customers · North American device makers · Domestic/European substrate manufacturers	 Knowledge technology required optimization to meet custom Integrated system from devired maintenance
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- up
- ired for customization and mer requirements
- elopment to production and
- nd to customer requests

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Business Overview : Wafer transport device

• We design and manufacture load ports that take wafers into various processing equipment mainly used in the frontend process of semiconductor manufacturing, wafer transfer robots that transfer wafers, and EFEMs that integrate them.

Semiconductor manufacturing process

transfer devices are primarily used

Design	Front-end process	Back-end process
 Design for circuit and pattern Photomask creation 	 Wafer fabrication Making circuit pattern Oxidation of wafer surface Thin film formation Pattern transcription of photomask Ion implantation 	 Dicing Die bonding Wire bonding Packaging Commercialization and final inspection

Image of our product installation



Multiple EFEM/load ports are used on a single line because multiple EFEM/load ports are installed at each processing unit.

Our main products



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Business Overview : PLP

• We design and manufacture conveyance equipment used in PLP, an advanced packaging technology that is expected to expand.

Semiconductor			Difference of packaging process		
Design Front-end process		Process in which our devices are primarily used Back-end process	Conventional packaging	Circuits are formed on wafters, and after cutting the chips into smaller pieces, they are individually bonded and encapsulated onto substrates to complete the product.	
 Design for circuit and pattern Photomask creation 	 Wafer fabrication Making circuit pattern Oxidation of wafer surface Thin film formation Pattern transcription of photomask Ion implantation 	 Dicing Die bonding Wire bonding Packaging Commercialization and final inspection 	WLP (Wafer Level Package)	After cutting the chips individually, only the good chips are rearranged on the wafer, and then they are bonded and encapsulated onto the substrate while the chips are still on the wafer. They are then cut individually.	
			PLP (Panel Level Package)	After cutting the chips individually, only the good chips are rearranged on a square-shaped panel, and then they are bonded and encapsulated onto the substrate while the chips are still on the panel. They are then cut individually.	
What is PLP	(Panel Level Packa	aging) about?	The chips that have been rearranged.	Panel	

- The packaging process involves rearranging numerous chips that have been individually cut after circuit formation onto thin. square-shaped substrates and then collectively molding them. This is a packaging technology called "PLP".
- In PLP, panel substrates larger than the standard 300mm wafer size, such as 510x515mm square, are commonly used.
- The panel substrate uses printed circuit boards, glass substrates for LCD panel manufacturing, and copper plates.

200mm

WLP

300mm

510 × 515mm

 600×600 mm

PIP

Hirata **Business Overview : Other Automatic Labor-saving Equipment**

• We manufacture products for various industrial fields such as organic EL vapor equipment, assembly equipment for home appliances, and medical physics and chemical equipment.

Main/New Fields of Other Automatic Labor-saving Equipment

Main field Medical physiology and chen equipment We manufacture a system for sample (pathological tissue specimen device automatic continuous thinning device	Main field Cal Assembly equipment for home appliances ests We manufacture all equipment, including massembly equipment built into high-perform home appliances.	notor mance We are contracted to manufacture vacuum evaporation equipment for OLED panels.	
 New field for monetization We are jointly developing a focused ultrasound treatment device targeting pancreatic cancer with SONIRE Therapeutics Inc (Headquartered in Shinjuku, Tokyo, hereinafter referred to as SONIRE) We aim for non-invasive cancer treatment that fuses SONIRE's Ultrasonic Technology with our retechnology. Clinical trials in humans have started, and we have begun development of the next generation or mass production equipment. 			

Main customers, competitors, superiority

Medical physiology and chemical equipment	Assembly equipment for home appliances	Organic EL Vapor equipment	 Hirata's superiority Extensive knowledge and expertise in production
Japan Customers Domestic medical specialty manufacturers	Asia Customers Asian home appliance manufacturers	Japan Customers Domestic manufacturing device manufacturers	 Integrated system from development to production and maintenance Engineering ability to respond to customer requests

Business Overview : High-Intensity Focused Ultrasound (HIFU) cancer treatment device

• We are applying our experience in specimen examination automation and robotics technology in the medical and scientific equipment field to enter the "treatment" domain.



- Hirata partners with SONIRE Therapeutics Inc. (SONIRE) in the medical and scientific equipment field.
- We conduct joint development of a cancer treatment device for clinical trials in humans (targeting inoperable pancreatic cancer)
- We develop device for minimally invasive treatment that does not involve skin incisions or organ removal.
- The devices are supplied to multiple domestic hospitals, and SONIRE are conducting domestic clinical trials. Hirata is providing after-sales service post-delivery.
- In the future, we aim to refine the device's safety, usability, and design, and work towards the development of mass-produced devices and the establishment of a mass production system.
- We are planning to expand overseas, aiming for early delivery to overseas hospitals and after-sales service at our overseas locations.

Please be aware that the performance forecasts and future predictions mentioned in this document are based on the information available to us at the time of its creation. They are subject to potential risks and uncertainties, such as changes in economic conditions, competition with other companies, and exchange rates. Therefore, please note that actual performance may significantly differ from the future outlook mentioned or described in this document due to various factors, including changes in the business environment.